

45 4580 03 MP T0,8

High-current contact elements

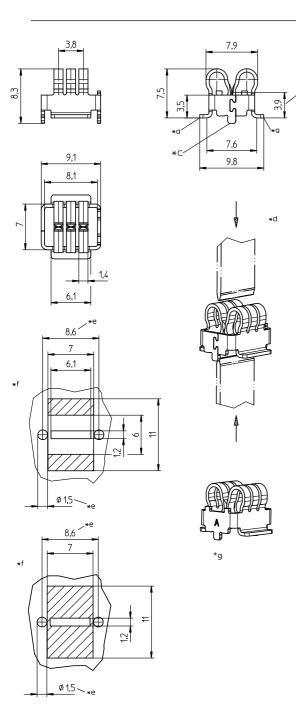


High-current contact bush with positioning pegs, in surface mount technology (SMT), mateable from top or bottom direction, for tab contacts 0.8–1.5 mm, for printed circuit boards or busbars

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Environmental conditions

Temperature range -40 °C/+120 °C

Materials

CuCr alloy, tin-plated Contact

Mechanical data

Mating with tab contact 5.3-7.2 mm x 0.8-

applicable for reflow soldering on

printed circuit board applicable for laser welding on a

busbar or lead frame

Mating cycles ≤ 5

Insertion force

tab contact 0.8 mm 22 N \pm 10 N - top or bottom entry tab contact 1.0 mm 22 N \pm 10 N - top or bottom entry tab contact 1.5 mm 35 N \pm 10 N - top or bottom entry ¹

09/2025

Withdrawal force 6 N +10/-3 N¹

¹ measured with polished steel test tabs

Electrical data (at Tamb 20 °C)

< 0.5 mΩ Contact resistance ≤ 60 A 1 Rated current

¹ depending on the connection to the printed circuit board/busbar, installation situation and heat

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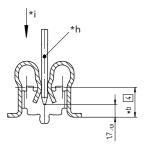


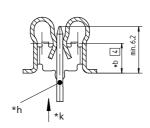
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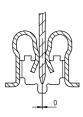
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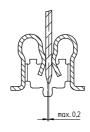
Assembly tolerances for top and bottom entry

- tab dimensions 4.8 mm x 0.8 mm x length 8 mm
- larger assembly tolerances possible for lengths > 15 mm



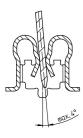


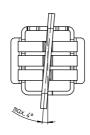




typical mating

permissible lateral offset





permissible tilt

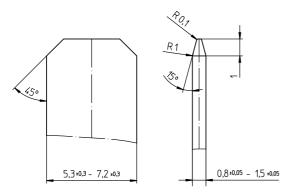
permissible twist

permissible combined tolerances tilt max. 2°, twist max. 2°



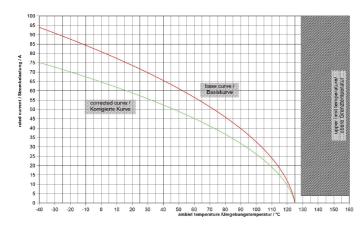
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Geometry of the mating tab contact



Material to be coordinated with Lumberg.

Derating diagram



Test setup: application example of a closed system, no air circulation, no heat dissipation

- tab contact: Cu-HCP, 7.5 mm x 1.0 mm
- connected wire: section 6 mm²
- ambient temperature: 20 °C

Further test configurations and details upon request.

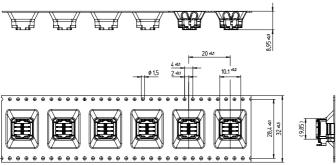


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Packaging

reel: 330 mm/110 mm/32,5 mm leader: 400 mm, 25 empty cavities trailer: 160 mm, 10 empty cavities





- *a supporting surface for soldering dimensions per solder pad min. 7.0 mm x 2.5 mm
- *b height contact point
- *c positioning peg
- *d mateable from top or bottom direction
- *e bore holes for positioning pegs
- *f circuit board layout (example)
- *g marking A for type 4580 03 MP T0,8
- *h contact tab
- *i mating from top direction
- *k mating from bottom direction



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Designation	Pole Number	PU (Pieces)	MDQ (Pieces)
4580 03 MP T0,8 V12VP12	1	350	2100

Packaging:

on reel